

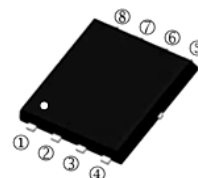
RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

The SSPR62N08S-C is the Shielded Gate Technology N-Ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The SSPR62N08S-C meet the RoHS and Green Product requirement with full function reliability approved.

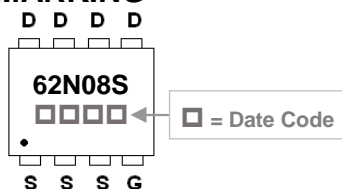
SPR-8PP



## FEATURES

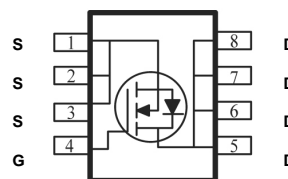
- Shielded Gate Trench Technology
- Lower Gate Charge
- Green Device Available

## MARKING



## PACKAGE INFORMATION

| Package | MPQ | Leader Size |
|---------|-----|-------------|
| SPR-8PP | 3K  | 13 inch     |



## ORDER INFORMATION

| Part Number  | Type                            |
|--------------|---------------------------------|
| SSPR62N08S-C | Lead (Pb)-free and Halogen-free |

## ABSOLUTE MAXIMUM RATINGS ( $T_J=25^{\circ}\text{C}$ unless otherwise specified)

| Parameter   | Symbol                   | Ratings                   | Unit                 |
|---|--------------------------|---------------------------|----------------------|
| Drain-Source Voltage                                    | $V_{DS}$                 | 80                        | V                    |
| Gate-Source Voltage                                     | $V_{GS}$                 | $\pm 20$                  | V                    |
| Continuous Drain Current (Silicon Limited) <sup>1</sup> | $I_D$                    | $T_C=25^{\circ}\text{C}$  | 62                   |
|   |                          | $T_C=100^{\circ}\text{C}$ | 39                   |
| Continuous Drain Current (Package Limited) <sup>1</sup> | $T_C=25^{\circ}\text{C}$ | 36                        | A                    |
| Pulsed Drain Current <sup>2</sup>                       | $I_{DM}$                 | 230                       | A                    |
| Power Dissipation <sup>3</sup>                          | $P_D$                    | 42                        | W                    |
| Operating Junction & Storage Temperature Range          | $T_J, T_{STG}$           | -55~150                   | $^{\circ}\text{C}$   |
| <b>Thermal Resistance Ratings</b>                       |                          |                           |                      |
| Thermal Resistance Junction-Ambient <sup>1</sup>        | $R_{\theta JA}$          | 50                        | $^{\circ}\text{C/W}$ |
| Thermal Resistance Junction-Case <sup>1</sup>           | $R_{\theta JC}$          | 3                         |                      |

**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

| Parameter                                      | Symbol        | Min.                    | Typ. | Max.      | Unit       | Test Condition   |                               |
|--|---------------|-------------------------|------|-----------|------------|--|-------------------------------|
| Drain-Source Breakdown Voltage                 | $V_{(BR)DSS}$ | 80                      | -    | -         | V          | $V_{GS}=0, I_D=250\mu\text{A}$   |                               |
| Gate-Threshold Voltage                         | $V_{GS(th)}$  | 1.4                     | -    | 2.4       | V          | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$  |                               |
| Forward Transconductance                       | $g_{fs}$      | -                       | 45   | -         | S          | $V_{DS}=5\text{V}, I_D=20\text{A}$   |                               |
| Zero Gate Voltage Drain Current                | $I_{DSS}$     | $T_J=25^\circ\text{C}$  | -    | -         | 1          | $\mu\text{A}$  | $V_{DS}=80\text{V}, V_{GS}=0$ |
|  |               | $T_J=100^\circ\text{C}$ | -    | -         | 100        |  |                               |
| Gate-Body Leakage Current                      | $I_{GSS}$     | -                       | -    | $\pm 100$ | nA         | $V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$  |                               |
| Static Drain-Source On-Resistance <sup>3</sup> | $R_{DS(ON)}$  | -                       | 5.2  | 5.9       | m $\Omega$ | $V_{GS}=10\text{V}, I_D=20\text{A}$  |                               |
|  |               | -                       | 7.5  | 9.5       |            | $V_{GS}=4.5\text{V}, I_D=20\text{A}$   |                               |
| Gate Resistance                                | $R_g$         | -                       | 1.1  | -         | $\Omega$   | $V_{GS}=0\text{V}, V_{DS}$ Open, $f=1\text{MHz}$                                 |                               |
| Total Gate Charge (4.5V)                       | $Q_g$         | -                       | 22   | -         | nC         | $V_{DD}=40\text{V}$<br>$V_{GS}=10\text{V}$<br>$I_D=20\text{A}$                   |                               |
| Total Gate Charge                              |               | -                       | 43   | -         |            |  |                               |
| Gate-Source Charge                             |               | $Q_{gs}$                | -    | 5         |            |  | -                             |
| Gate-Drain Charge                              |               | $Q_{gd}$                | -    | 14        |            |  | -                             |
| Turn-on Delay Time                             | $T_{d(on)}$   | -                       | 10   | -         | nS         | $V_{DS}=40\text{V}$<br>$V_{GS}=10\text{V}$<br>$I_D=20\text{A}$<br>$R_G=10\Omega$ |                               |
| Rise Time                                      | $T_r$         | -                       | 8    | -         |            |  |                               |
| Turn-off Delay Time                            | $T_{d(off)}$  | -                       | 32   | -         |            |  |                               |
| Fall Time                                      | $T_f$         | -                       | 10   | -         |            |  |                               |
| Input Capacitance                              | $C_{iss}$     | -                       | 2164 | -         | pF         | $V_{DS}=40\text{V}$<br>$V_{GS}=0$<br>$f=1\text{MHz}$                             |                               |
| Output Capacitance                             | $C_{oss}$     | -                       | 540  | -         |            |  |                               |
| Reverse Transfer Capacitance                   | $C_{rss}$     | -                       | 17   | -         |            |  |                               |
| <b>Drain-Source Diode</b>                      |               |                         |      |           |            |  |                               |
| Diode Forward Voltage <sup>3</sup>             | $V_{SD}$      | -                       | 0.9  | 1.2       | V          | $V_{GS}=0, I_F=20\text{A}$   |                               |
| Reverse Recovery Time                          | $T_{rr}$      | -                       | 33   | -         | nS         | $I_F=20\text{A}, V_R=40\text{V},$<br>$di_F/dt=400\text{A}/\mu\text{S}$           |                               |
| Reverse Recovery Charge                        | $Q_{rr}$      | -                       | 99   | -         | nC         |  |                               |

Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2oz copper.
- The Pulse width limited by maximum junction temperature, Pulse Width $\leq 300\mu\text{s}$ , Duty Cycles $\leq 2\%$ .
- The Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycles $\leq 2\%$ .

**CHARACTERISTICS CURVE**

Fig 1. Typical Output Characteristics

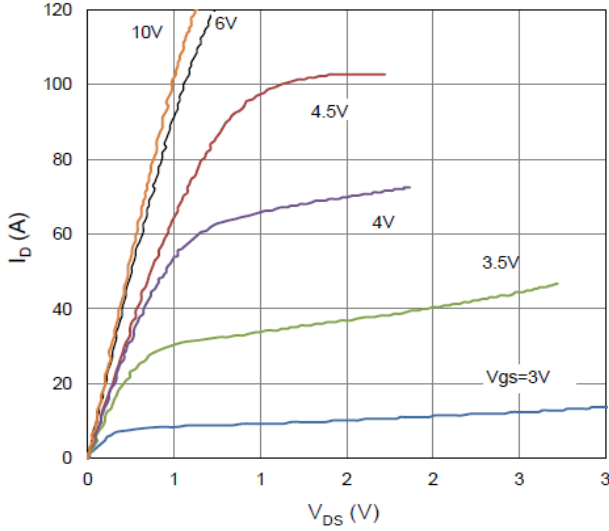


Figure 2. On-Resistance vs. Gate-Source Voltage

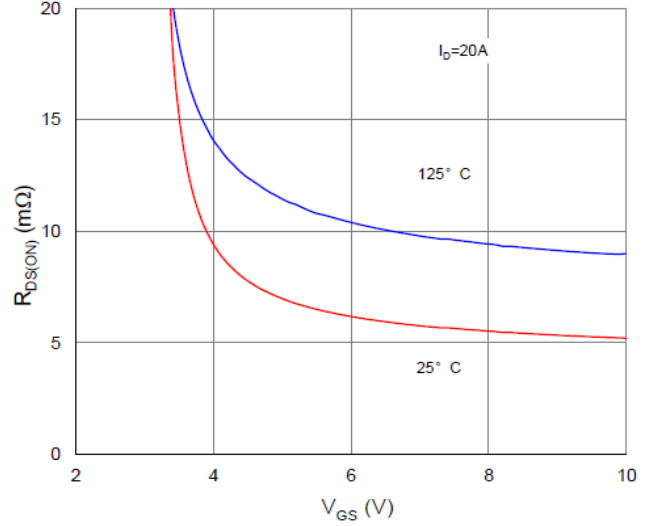


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

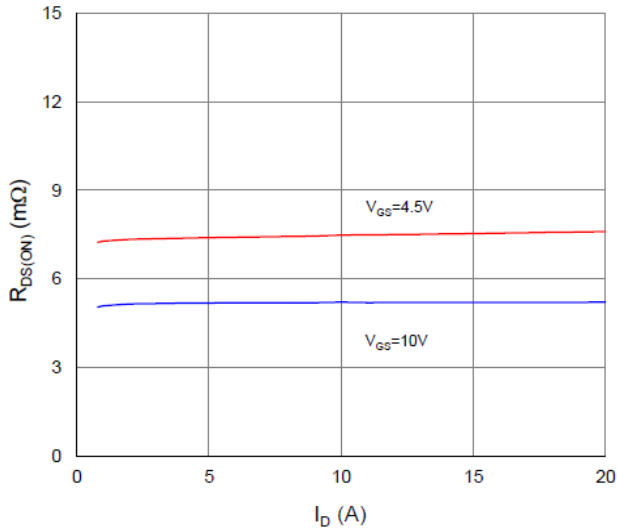


Figure 4. Normalized On-Resistance vs. Junction Temperature

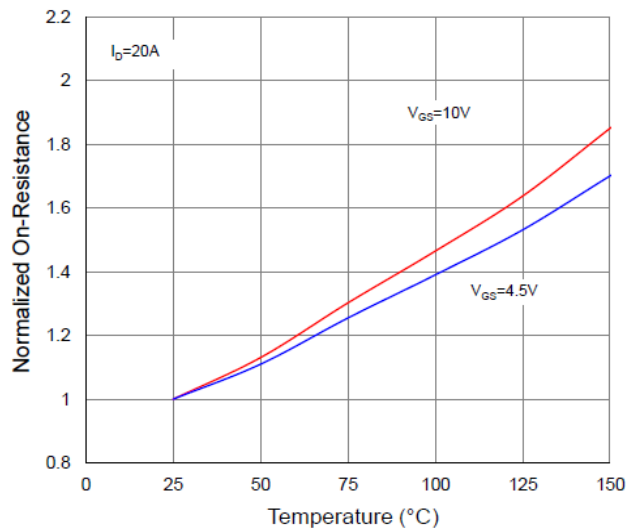


Figure 5. Typical Transfer Characteristics

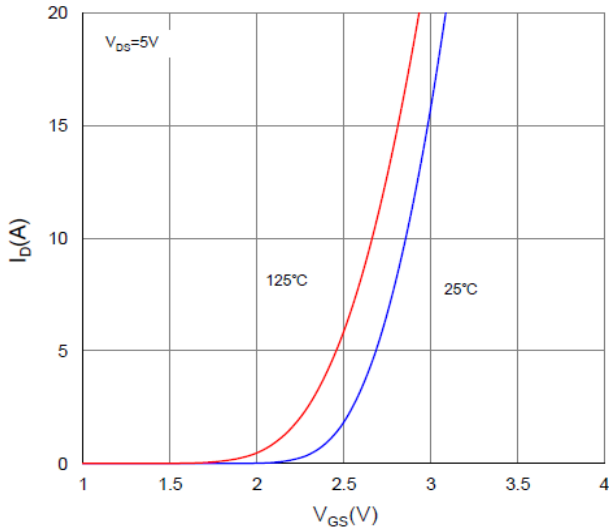
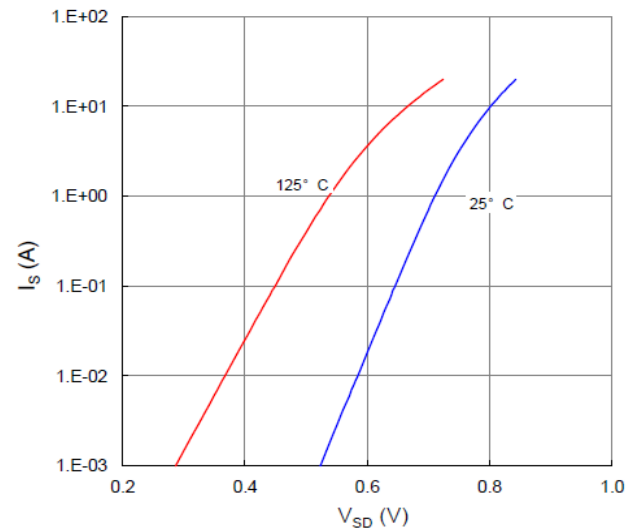


Figure 6. Typical Source-Drain Diode Forward Voltage



**CHARACTERISTICS CURVE**

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

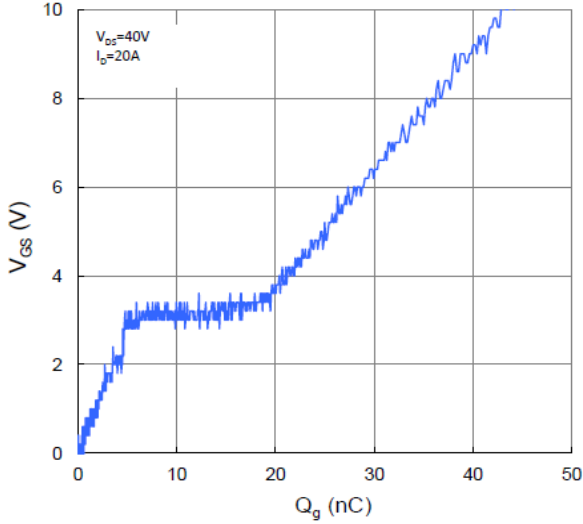


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

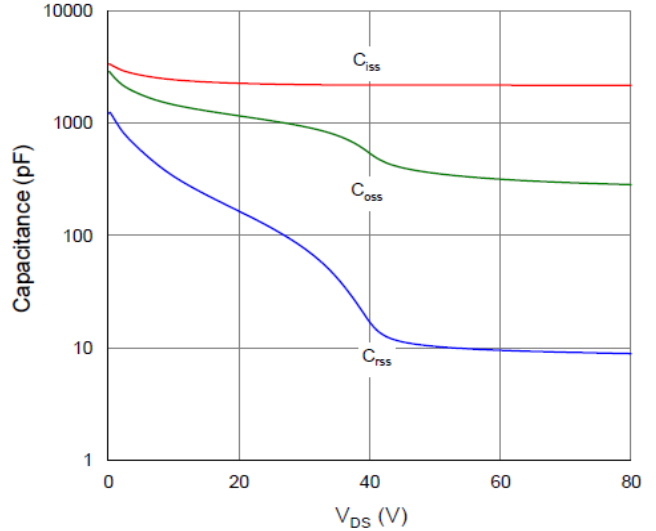


Figure 9. Maximum Safe Operating Area

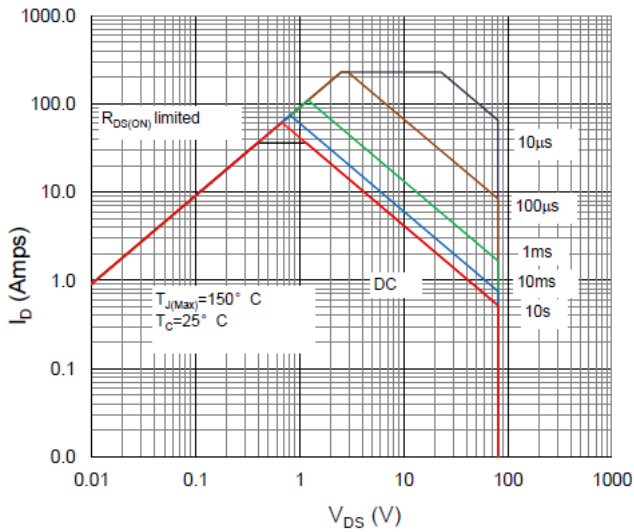


Figure 10. Maximum Drain Current vs. Case Temperature

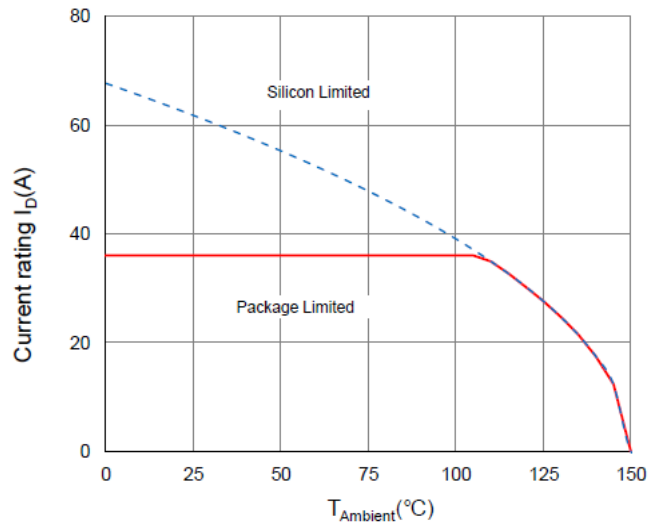
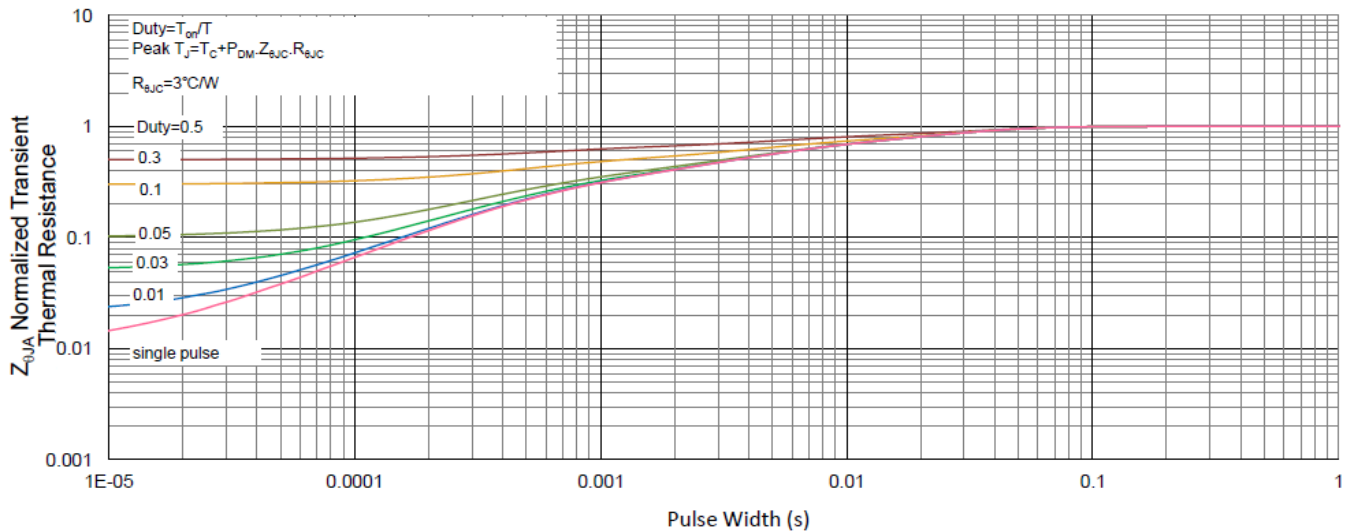
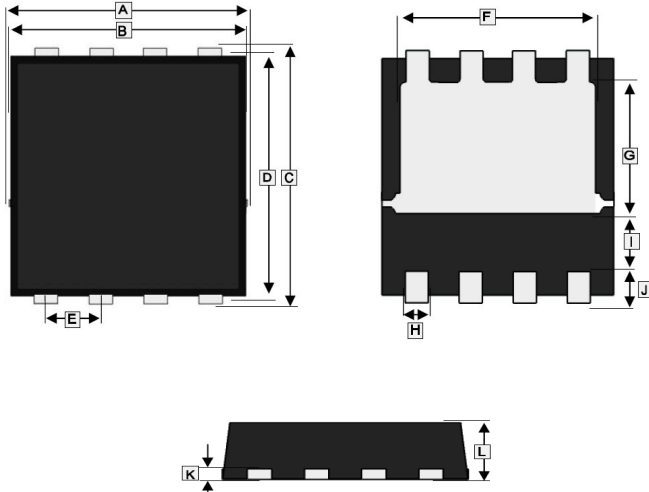


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



**PACKAGE OUTLINE DIMENSIONS**

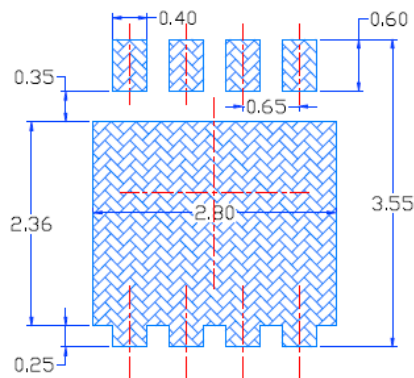
**SPR-8PP**



| REF. | Millimeter |      |
|------|------------|------|
|      | Min.       | Max. |
| A    | 3.00       | 3.40 |
| B    | 3.00       | 3.25 |
| C    | 3.20       | 3.45 |
| D    | 3.00       | 3.20 |
| E    | 0.65 BSC.  |      |
| F    | 2.39       | 2.60 |
| G    | 1.35       | 1.98 |
| H    | 0.24       | 0.35 |
| I    | 0.35 TYP.  |      |
| J    | 0.60 TYP.  |      |
| K    | 0.10       | 0.25 |
| L    | 0.70       | 0.90 |

**MOUNTING PAD LAYOUT**

**SPR-8PP**



\*Dimensions in millimeters